

RELAY PCB PROCESS NOTES

When suffix "E" is specified for Epoxy Seal, refer to AZ "Relay Technical Notes" on AZ website-Product Resources. Consult factory for other PCB process conditions that may apply.

See Key Points Below:

Preheating

In order to improve the soldering performance, recommended temperature and time for preheat is 100°C (212°F) or less for duration of approximately 1 minute. Exposing relays to high temperatures for long periods of time may affect relay characteristics.

Soldering

Soldering precautions seen in table below.

Automatic Soldering	Manual Soldering
<ul style="list-style-type: none"> ● To maintain soldering stability, the suggested soldering method is wave solder. ● Adjust the height of the flux liquid level as to prevent overflow of the PCB. ● A solder temperature to not exceed 270°C (518°F) Max. 	<ul style="list-style-type: none"> ● Always keep the tip of the soldering iron clean to prevent contamination of the solder. ● Suggested soldering conditions: <ul style="list-style-type: none"> Wattage range 30 -60W Temperature approximately 300°(572°F) Soldering duration approximately 3 seconds Rosin flux recommended

Cooling

Prompt air cooling is recommended as it prevents deterioration of the relay due to the soldering heat. Avoid immersing a relay into cold liquids immediately after soldering as it may damage the hermetic characteristics of the relay.

Cleaning

Please select the cleaning method in the table below when cleaning.

Dust Protected Type	Flux Proofed Type	Plastic Sealed Type
<ul style="list-style-type: none"> ● Cleaning by immersion is not recommended. 		<ul style="list-style-type: none"> ● Sealed relays can be safely cleaned by immersion. ● Use of pressure or agitation water wash must use extreme care. ● Ultrasonic cleaning is not recommended as it may cause problems such as breaks in the coil or slight sticking of the contacts.

More details available on AZ website under http://www.azettler.com/pdfs/technical_notes.pdf